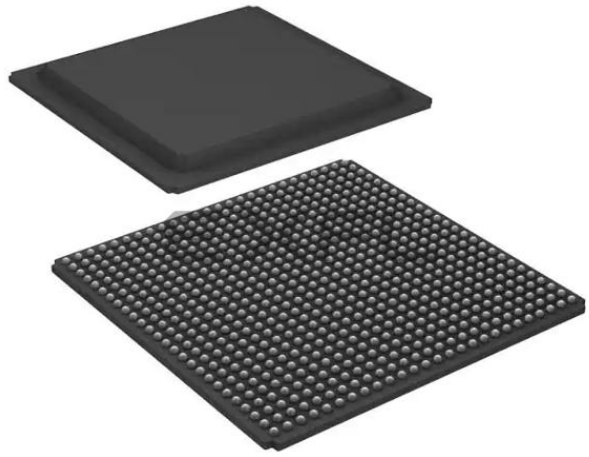

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2400
Number of Logic Elements/Cells	10800
Total RAM Bits	573440
Number of I/O	404
Number of Gates	129600
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv405e-7fg676c

Table 1: **Virtex-E Extended Memory Field-Programmable Gate Array Family Members**

Device	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	BlockRAM Bits	Distributed RAM Bits
XCV405E	129,600	40 x 60	10,800	183	404	573,440	153,600
XCV812E	254,016	56 x 84	21,168	201	556	1,146,880	301,056

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectI/O technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT}, the supply voltage for the internal logic and memory, is 1.8 V, instead of 2.5 V for Virtex devices. Advanced processing and 0.18 µm design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3 V tolerant, and can be 5 V tolerant with an external 100 Ω resistor. PCI 5 V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT}. With Virtex-E devices, the LVTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO}.

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 µm CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex-E family includes the nine members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series™ and Alliance Series™ Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architechtures. Virtex-E I/Os comply fully with 3.3 V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz. Table 2, page 3, shows performance data for representative circuits, using worst-case timing parameters.

Dedicated Routing

Some signal classes require dedicated routing resources to maximize performance. In the Virtex-E architecture, dedicated routing resources are provided for two signal classes.

- Horizontal routing resources are provided for on-chip 3-state busses. Four partitionable bus lines are provided per CLB row, permitting multiple busses within a row, as shown in Figure 8.
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB. Global Clock Distribution Network.
- DLL Location

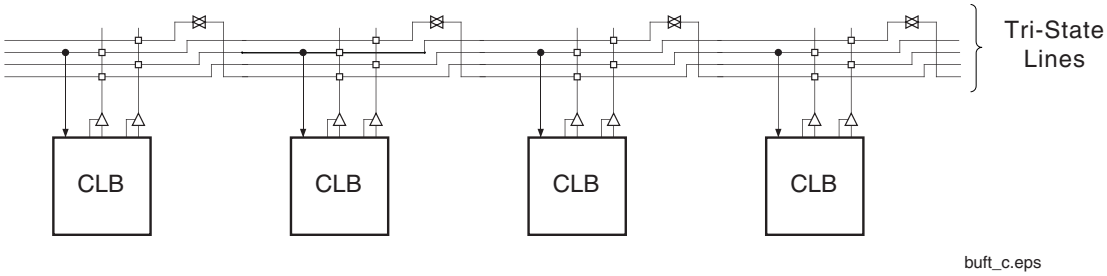

Figure 8: **BUFT Connections to Dedicated Horizontal Bus LInes**

Clock Routing

Clock Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex-E devices include two tiers of clock routing resources referred to as global and local clock routing resources.

- The global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The global nets can be driven only by global buffers. There are four global buffers, one for each global net.
- The local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These local resources are more flexible than the global resources since they are not restricted to routing only to clock pins.

Global Clock Distribution

Virtex-E provides high-speed, low-skew clock distribution through the global routing resources described above. A typical clock distribution net is shown in Figure 9.

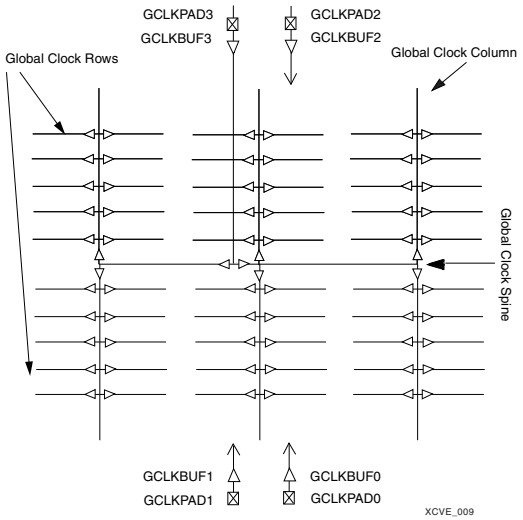

Figure 9: **Global Clock Distribution Network**

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is selected either from these pads or from signals in the general purpose routing.

Digital Delay-Locked Loops

There are eight DLLs (Delay-Locked Loops) per device, with four located at the top and four at the bottom, Figure 10. The DLLs can be used to eliminate skew between the clock input pad and the internal clock input pins throughout the device. Each DLL can drive two global clock networks.The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Additional delay is introduced such that clock edges arrive at internal flip-flops synchronized with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The

Table 6: **Boundary Scan Instructions**

Boundary-Scan Command	Binary Code (4:0)	Description
EXTEST	00000	Enable boundary-scan EXTEST operation.
SAMPLE/ PRELOAD	00001	Enable boundary-scan SAMPLE/PRELOAD operation.
USER1	00010	Access user-defined register 1.
USER2	00011	Access user-defined register 2.
CFG_OUT	00100	Access the configuration bus for read operations.
CFG_IN	00101	Access the configuration bus for write operations.
INTEST	00111	Enable boundary-scan INTEST operation.
USERCODE	01000	Enable shifting out USER code.
IDCODE	01001	Enable shifting out of ID Code.
HIGHZ	01010	3-state output pins while enabling the Bypass Register.
JSTART	01100	Clock the start-up sequence when StartupClk is TCK.
BYPASS	11111	Enable BYPASS.
RESERVED	All other codes	Xilinx reserved instructions.

Instruction Set

The Virtex-E Series boundary scan instruction set also includes instructions to configure the device and read back configuration data (CFG_IN, CFG_OUT, and JSTART). The complete instruction set is coded as shown in Table 6.

Data Registers

The primary data register is the boundary scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out, and 3-State Control. Non-IOB pins have appropriate partial bit population if input-only or output-only. Each EXTEST CAPTURED-OR state captures all In, Out, and 3-state pins.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream boundary scan device.

The FPGA supports up to two additional internal scan chains that can be specified using the BSCAN macro. The macro provides two user pins (SEL1 and SEL2) which are decodes of the USER1 and USER2 instructions respectively. For these instructions, two corresponding pins (T DO1 and TDO2) allow user scan data to be shifted out of TDO.

Likewise, there are individual clock pins (DRCK1 and DRCK2) for each user register. There is a common input pin (TDI) and shared output pins that represent the state of the TAP controller (RESET, SHIFT, and UPDATE).

Bit Sequence

The order within each IOB is: In, Out, 3-State. The input-only pins contribute only the In bit to the boundary scan I/O data register, while the output-only pins contributes all three bits.

From a cavity-up view of the chip (as shown in EPIC), starting in the upper right chip corner, the boundary scan data-register bits are ordered as shown in Figure 12.

BSDL (Boundary Scan Description Language) files for Virtex-E Series devices are available on the Xilinx web site in the File Download area.

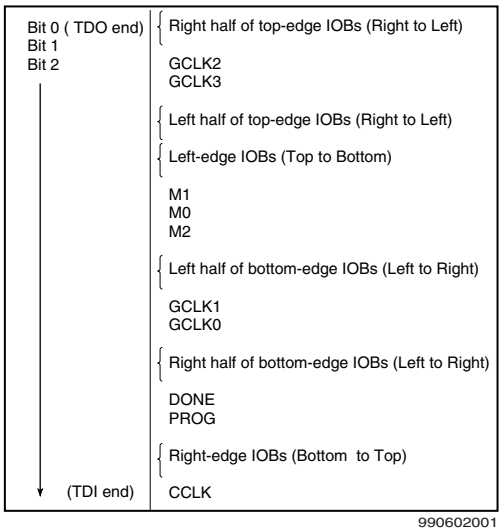

Figure 12: **Boundary Scan Bit Sequence**

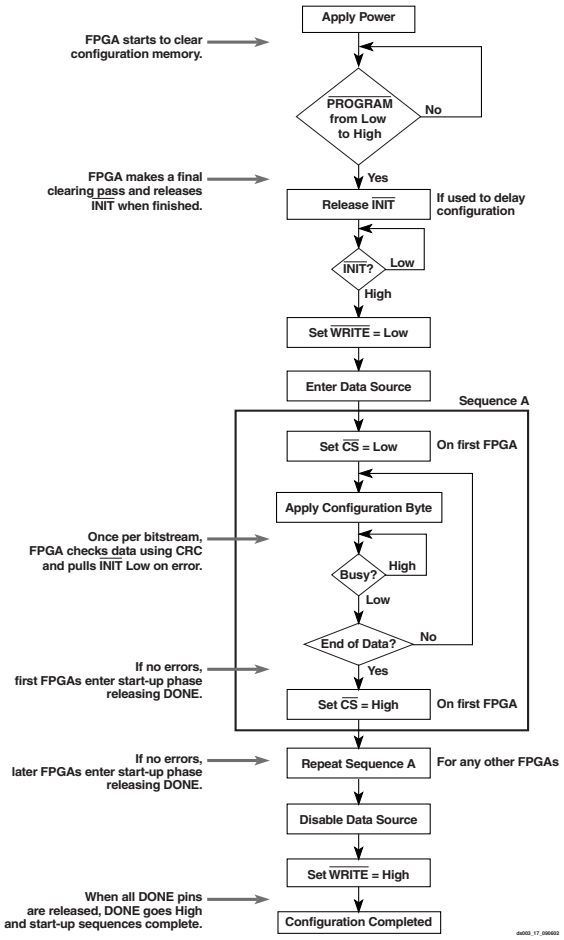

Figure 18: **SelectMAP Flowchart for Write Operations**

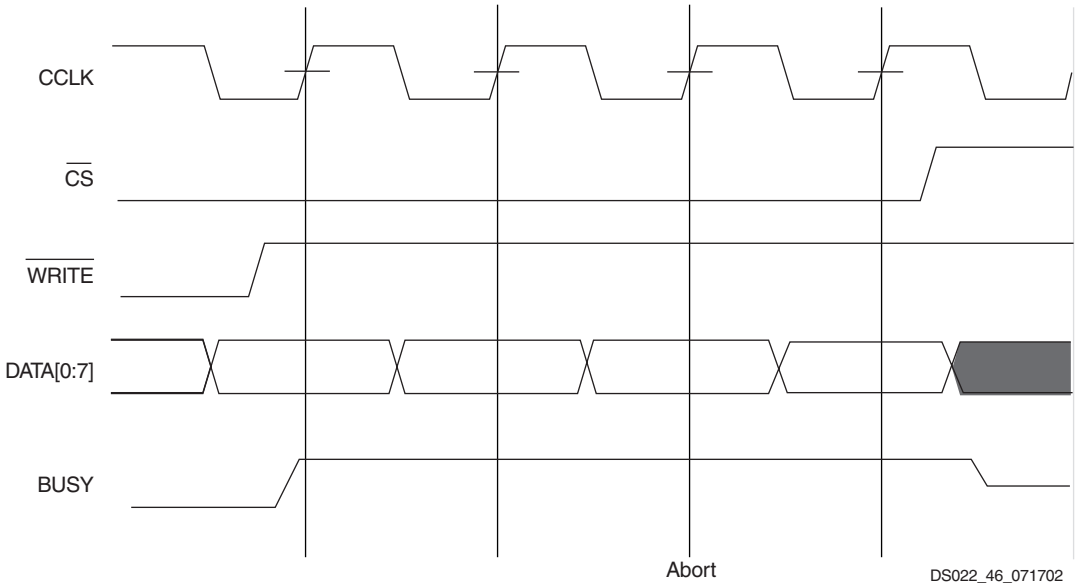

Figure 19: **SelectMAP Write Abort Waveforms**

Boundary-Scan Mode

In the boundary-scan mode, configuration is done through the IEEE 1149.1 Test Access Port. Note that the PROGRAM pin must be pulled High prior to reconfiguration. A Low on the PROGRAM pin resets the TAP controller and no JTAG operations can be performed.

Design Considerations

This section contains more detailed design information on the following features.

Using DLLs

The Virtex-E FPGA series provides up to eight fully digital dedicated on-chip Delay-Locked Loop (DLL) circuits which provide zero propagation delay, low clock skew between output clock signals distributed throughout the device, and advanced clock domain control. These dedicated DLLs can be used to implement several circuits which improve and simplify system level design.

Introduction

As FPGAs grow in size, quality on-chip clock distribution becomes increasingly important. Clock skew and clock delay impact device performance and the task of managing clock skew and clock delay with conventional clock trees becomes more difficult in large devices. The Virtex-E series of devices resolve this potential problem by providing up to eight fully digital dedicated on-chip DLL circuits which provide zero propagation delay and low clock skew between output clock signals distributed throughout the device.

Each DLL can drive up to two global clock routing networks within the device. The global clock distribution network minimizes clock skews due to loading differences. By monitoring a sample of the DLL output clock, the DLL can compensate for the delay on the routing network, effectively eliminating the delay from the external input port to the individual clock loads within the device.

In addition to providing zero delay with respect to a user source clock, the DLL can provide multiple phases of the source clock. The DLL can also act as a clock doubler or it can divide the user source clock by up to 16.

Clock multiplication gives the designer a number of design alternatives. For instance, a 50 MHz source clock doubled by the DLL can drive an FPGA design operating at 100 MHz. This technique can simplify board design because the clock path on the board no longer distributes such a high-speed signal. A multiplied clock also provides designers the option of time-domain-multiplexing, using one circuit twice per clock cycle, consuming less area than two copies of the same circuit. Two DLLs in can be connected in series to increase the effective clock multiplication factor to four.

The DLL can also act as a clock mirror. By driving the DLL output off-chip and then back in again, the DLL can be used to de-skew a board level clock between multiple devices.

In order to guarantee the system clock establishes prior to the device “waking up,” the DLL can delay the completion of the device configuration process until after the DLL achieves lock.

By taking advantage of the DLL to remove on-chip clock delay, the designer can greatly simplify and improve system level design involving high-fanout, high-performance clocks.

Library DLL Symbols

Figure 21 shows the simplified Xilinx library DLL macro symbol, BUFGDLL. This macro delivers a quick and efficient way to provide a system clock with zero propagation delay throughout the device. Figure 22 and Figure 23 show the two library DLL primitives. These symbols provide access to the complete set of DLL features when implementing more complex applications.

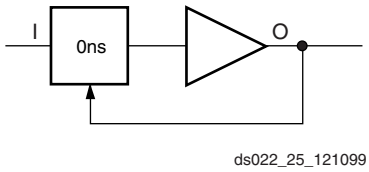

Figure 21: **Simplified DLL Macro Symbol BUFGDLL**

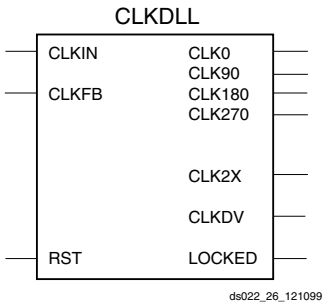

Figure 22: **Standard DLL Symbol CLKDLL**

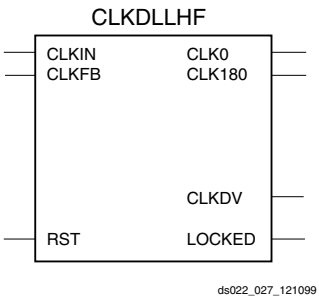

Figure 23: **High Frequency DLL Symbol**

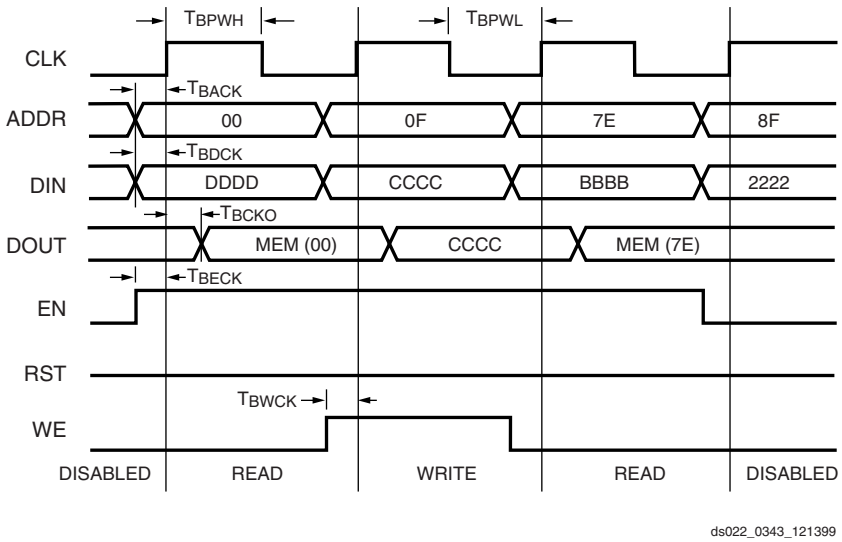

Figure 33: **Timing Diagram for Single Port Block SelectRAM+ Memory**

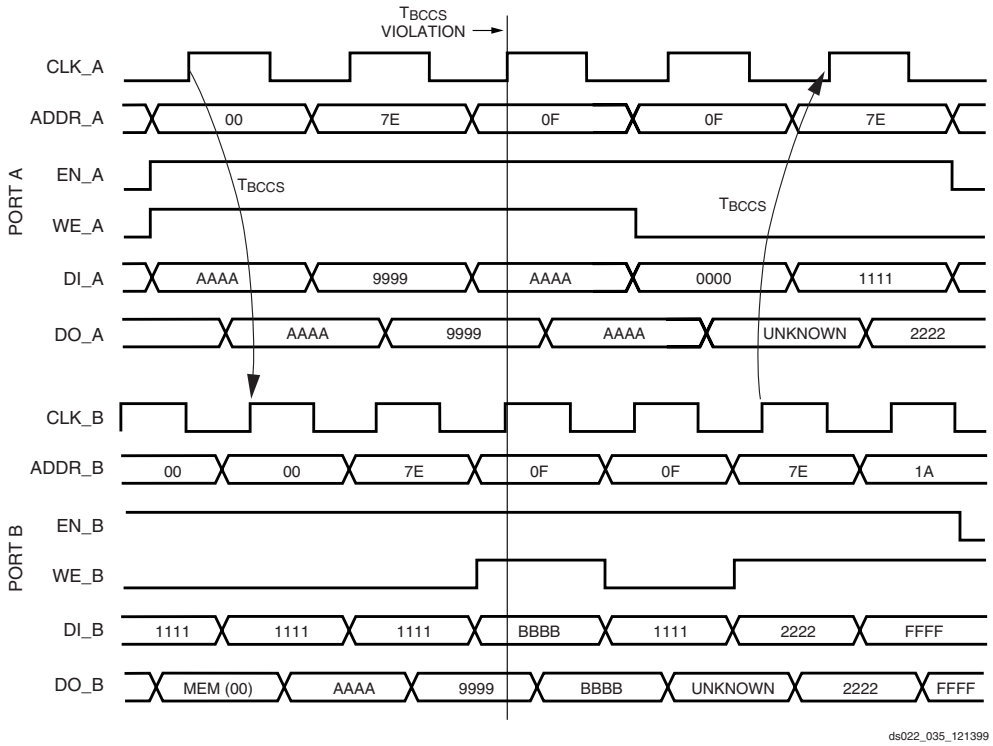

Figure 34: **Timing Diagram for a True Dual-port Read/Write Block SelectRAM+ Memory**

At the third rising edge of CLKA, the T_{BCCS} parameter is violated with two writes to memory location 0x0F. The DOA and DOB busses reflect the contents of the DIA and DIB busses, but the stored value at 0x0F is invalid.

At the fourth rising edge of CLKA, a read operation is performed at memory location 0x0F and invalid data is present on the DOA bus. Port B also executes a read operation to memory location 0x0F and also reads invalid data.

At the fifth rising edge of CLKA a read operation is performed that does not violate the T_{BCCS} parameter to the previous write of 0x7E by Port B. THe DOA bus reflects the recently written value by Port B.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

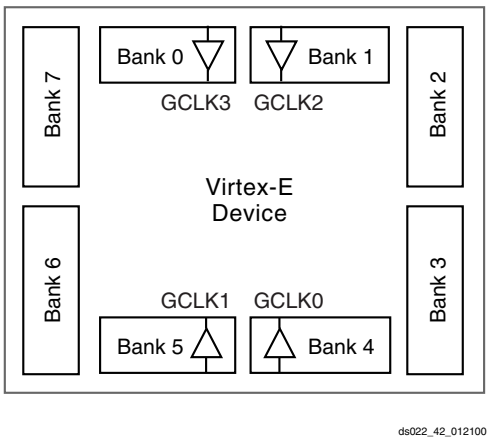

Figure 38: **Virtex-E I/O Banks**

Table 19: **Xilinx Input Standards Compatibility Requirements**

Rule 1	Standards with the same input V_{CCO}, output V_{CCO}, and V_{REF} can be placed within the same bank.

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG should only drive a CLKDLL, CLKDLLHF, or a BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

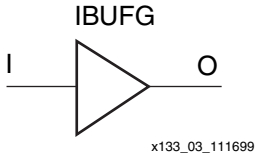

Figure 39: **Virtex-E Global Clock Input Buffer (IBUFG) Symbol**

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is “banked” within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

Input termination techniques include the following:

- None
- Parallel (Shunt)

These termination techniques can be applied in any combination. A generic example of each combination of termination methods appears in Figure 43.

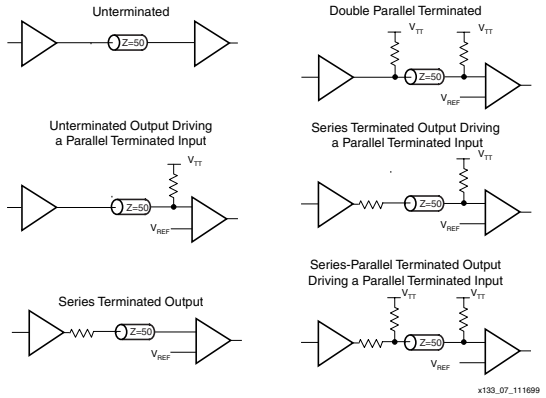

Figure 43: **Overview of Standard Input and Output Termination Methods**

Simultaneous Switching Guidelines

Ground bounce can occur with high-speed digital ICs when multiple outputs change states simultaneously, causing undesired transient behavior on an output, or in the internal logic. This problem is also referred to as the Simultaneous Switching Output (SSO) problem.

Ground bounce is primarily due to current changes in the combined inductance of ground pins, bond wires, and ground metallization. The IC internal ground level deviates from the external system ground level for a short duration (a few nanoseconds) after multiple outputs change state simultaneously.

Ground bounce affects stable Low outputs and all inputs because they interpret the incoming signal by comparing it to the internal ground. If the ground bounce amplitude exceeds the actual instantaneous noise margin, then a non-changing input can be interpreted as a short pulse with a polarity opposite to the ground bounce.

Table 21 provides the guidelines for the maximum number of simultaneously switching outputs allowed per output power/ground pair to avoid the effects of ground bounce. Refer to Table 22 for the number of effective output power/ground pairs for each Virtex-E device and package combination.

Table 21: **Guidelines for Maximum Number of Simultaneously Switching Outputs per Power/Ground Pair**

Standard	Package
	BGA, FGA
LVTTL Slow Slew Rate, 2 mA drive	68
LVTTL Slow Slew Rate, 4 mA drive	41
LVTTL Slow Slew Rate, 6 mA drive	29
LVTTL Slow Slew Rate, 8 mA drive	22
LVTTL Slow Slew Rate, 12 mA drive	17
LVTTL Slow Slew Rate, 16 mA drive	14
LVTTL Slow Slew Rate, 24 mA drive	9
LVTTL Fast Slew Rate, 2 mA drive	40
LVTTL Fast Slew Rate, 4 mA drive	24
LVTTL Fast Slew Rate, 6 mA drive	17
LVTTL Fast Slew Rate, 8 mA drive	13
LVTTL Fast Slew Rate, 12 mA drive	10
LVTTL Fast Slew Rate, 16 mA drive	8
LVTTL Fast Slew Rate, 24 mA drive	5
LVCMOS	10
PCI	8
GTL	4
GTL+	4
HSTL Class I	18
HSTL Class III	9
HSTL Class IV	5
SSTL2 Class I	15
SSTL2 Class II	10
SSTL3 Class I	11
SSTL3 Class II	7
CTT	14
AGP	9

Note: This analysis assumes a 35 pF load for each output.

Table 22: **Virtex-E Extended Memory Family Equivalent Power/Ground Pairs**

Pkg/Part	XCV405E	XCV812E
BG560		56
FG676	56	
FG900		

LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 34.

Table 34: **LVTTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	2.0	-	3.6
V_{IL}	–0.5	-	0.8
V_{OH}	2.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–24	-	-
I_{OL}at V_{OL} (mA)	24	-	-

Note: $V_{OL}$and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 35.

Table 35: **LVCMOS2 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.7	-	3.6
V_{IL}	–0.5	-	0.7
V_{OH}	1.9	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–12	-	-
I_{OL}at V_{OL} (mA)	12	-	-

LVCMOS18

LVCMOS18 does not require termination. Table 36 lists DC voltage specifications.

Table 36: **LVCMOS18 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	1.70	1.80	1.90
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	0.65 x V_{CCO}	-	1.95
V_{IL}	– 0.5	-	0.2 x V_{CCO}
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 37.

Table 37: **AGP-2X Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}$(1)	1.17	1.32	1.48
V_{TT}	-	-	-
$V_{IH} = V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} = V_{REF} – 0.2$	-	1.12	1.28
$V_{OH} = 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} = 0.1 \times V_{CCO}$	-	0.33	0.36
I_{OH} at V_{OH} (mA)	Note 2	-	-
I_{OL}at V_{OL} (mA)	Note 2	-	-

Notes:
1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

Virtex-E Extended Memory Data Sheet

The Virtex-E Extended Memory Data Sheet contains the following modules:

- DS025-1, Virtex-E 1.8V Extended Memory FPGAs: **Introduction and Ordering Information (Module 1)**
- DS025-2, Virtex-E 1.8V Extended Memory FPGAs: **Functional Description (Module 2)**
- DS025-3, Virtex-E 1.8V Extended Memory FPGAs: **DC and Switching Characteristics (Module 3)**
- DS025-4, Virtex-E 1.8V Extended Memory FPGAs: **Pinout Tables (Module 4)**

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, min	V, max	V, min	V, max	V, Max	V, Min	mA	mA
LVTTL(1)	– 0.5	0.8	2.0	3.6	0.4	2.4	24	– 24
LVCMOS2	– 0.5	0.7	1.7	2.7	0.4	1.9	12	– 12
LVCMOS18	– 0.5	20% V_{CCO}	70% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	– 8
PCI, 3.3 V	– 0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	– 0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	n/a	40	n/a
GTL+	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	n/a	36	n/a
HSTL I(3)	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8
HSTL III	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.80	V_{REF} + 0.80	15.2	–15.2
CTT	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.4	V_{REF} + 0.4	8	–8
AGP	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:
1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on www.xilinx.com.

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
NA	VCCINT	B18
NA	VCCINT	B28
NA	VCCINT	C22
NA	VCCINT	C24
NA	VCCINT	E9
NA	VCCINT	E12
NA	VCCINT	F2
NA	VCCINT	H30
NA	VCCINT	J1
NA	VCCINT	K32
NA	VCCINT	M3
NA	VCCINT	N1
NA	VCCINT	N29
NA	VCCINT	N33
NA	VCCINT	U5
NA	VCCINT	U30
NA	VCCINT	Y2
NA	VCCINT	Y31
NA	VCCINT	AB2
NA	VCCINT	AB32
NA	VCCINT	AD2
NA	VCCINT	AD32
NA	VCCINT	AG3
NA	VCCINT	AG31
NA	VCCINT	AJ13
NA	VCCINT	AK8
NA	VCCINT	AK11
NA	VCCINT	AK17
NA	VCCINT	AK20
NA	VCCINT	AL14
NA	VCCINT	AL22
NA	VCCINT	AL27
NA	VCCINT	AN25
0	VCCO	A22
0	VCCO	A26
0	VCCO	A30

Table 1: **BG560 BGA — XCV405E and XCV812E**

Bank	Pin Description	Pin#
0	VCCO	B19
0	VCCO	B32
1	VCCO	A10
1	VCCO	A16
1	VCCO	B13
1	VCCO	C3
1	VCCO	E5
2	VCCO	B2
2	VCCO	D1
2	VCCO	H1
2	VCCO	M1
2	VCCO	R2
3	VCCO	V1
3	VCCO	AA2
3	VCCO	AD1
3	VCCO	AK1
3	VCCO	AL2
4	VCCO	AN4
4	VCCO	AN8
4	VCCO	AN12
4	VCCO	AM2
4	VCCO	AM15
5	VCCO	AL31
5	VCCO	AM21
5	VCCO	AN18
5	VCCO	AN24
5	VCCO	AN30
6	VCCO	W32
6	VCCO	AB33
6	VCCO	AF33
6	VCCO	AK33
6	VCCO	AM32
7	VCCO	C32
7	VCCO	D33
7	VCCO	K33
7	VCCO	N32
7	VCCO	T33

BG560 Differential Pin Pairs

Virtex-E Extended Memory devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package.

Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair is in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 2: **BG560 Package Differential Pin Pair Summary XCV405E and XCV812E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	A17	C18	NA	IO LVDS 21
2	1	D17	E17	NA	IO LVDS 21
1	5	AJ17	AM18	NA	IO LVDS 115
0	4	AL17	AM17	NA	IO LVDS 115
IO LVDS Total Outputs: 183, Asyncronous Outputs: 79					
0	0	D29	E28	NA	-
1	0	A31	D28	√	-
2	0	C29	E27	√	VREF_0
3	0	D27	B30	1	-
4	0	B29	E26	√	-
5	0	C27	D26	√	VREF_0
6	0	A28	E25	NA	-
7	0	C26	D25	1	-
8	0	B26	E24	1	VREF_0
9	0	D24	C25	1	-
10	0	A25	E23	√	VREF_0
11	0	B24	D23	√	-
12	0	C23	E22	NA	-
13	0	D22	A23	√	-
14	0	B22	E21	√	VREF_0
15	0	C21	D21	1	-
16	0	E20	B21	√	-
17	0	C20	D20	√	VREF_0
18	0	E19	B20	NA	-
19	0	C19	D19	1	-
20	0	D18	A19	1	VREF_0
21	1	E17	C18	NA	GCLK LVDS 3/2
22	1	B17	C17	1	-
23	1	D16	B16	1	VREF_1
24	1	C16	E16	1	-
25	1	C15	A15	NA	-
26	1	E15	D15	√	VREF_1
27	1	D14	C14	√	-
28	1	E14	A13	1	-
29	1	D13	C13	√	VREF_1
30	1	E13	C12	√	-
31	1	D12	A11	NA	-
32	1	C11	B11	√	-
33	1	D11	B10	√	VREF_1
34	1	A9	C10	2	-
35	1	D10	C9	1	VREF_1
36	1	B8	A8	1	-
37	1	C8	E10	NA	-
38	1	A6	B7	√	VREF_1
39	1	D8	C7	√	-
40	1	B5	A5	2	-
41	1	D7	C6	√	VREF_1
42	1	B4	A4	√	-
43	1	E7	C5	NA	-
44	1	A2	D6	√	CS
45	2	D4	E4	√	DIN_D0
46	2	F5	B3	2	-
47	2	F4	C1	NA	-
48	2	G5	E3	1	VREF_2
49	2	D2	G4	1	-

Table 2: **BG560 Package Differential Pin Pair Summary XCV405E and XCV812E**

118	5	AK19	AM20	NA	-
119	5	AJ19	AL20	√	VREF_5
120	5	AN21	AL21	√	-
121	5	AJ20	AM22	1	-
122	5	AK21	AN23	√	VREF_5
123	5	AJ21	AM23	√	-
124	5	AK22	AM24	NA	-
125	5	AL23	AJ22	√	-
126	5	AK23	AL24	√	VREF_5
127	5	AN26	AJ23	2	-
128	5	AK24	AM26	1	VREF_5
129	5	AM27	AJ24	1	-
130	5	AL26	AK25	NA	-
131	5	AN29	AJ25	√	VREF_5
132	5	AK26	AM29	√	-
133	5	AM30	AJ26	2	-
134	5	AK27	AL29	√	VREF_5
135	5	AN31	AJ27	√	-
136	5	AM31	AK28	NA	-
137	6	AJ30	AH29	√	-
138	6	AH30	AK31	2	-
139	6	AJ31	AG29	NA	-
140	6	AG30	AK32	1	VREF_6
141	6	AF29	AH31	1	-
142	6	AF30	AH32	NA	-
143	6	AH33	AE29	√	VREF_6
144	6	AE30	AG33	2	-
145	6	AF32	AD29	NA	-
146	6	AD30	AE31	NA	VREF_6
147	6	AC29	AE32	NA	-
148	6	AC30	AD31	√	VREF_6
149	6	AC31	AB29	√	-
150	6	AB30	AC33	2	-
151	6	AA29	AB31	NA	-

Table 2: **BG560 Package Differential Pin Pair Summary XCV405E and XCV812E**

152	6	AA31	AA30	1	VREF_6
153	6	Y29	AA32	1	-
154	6	Y30	AA33	NA	-
155	6	W29	Y32	√	VREF_6
156	6	W31	W30	2	-
157	6	V30	W33	NA	-
158	6	V31	V29	NA	VREF_6
159	6	U33	V32	NA	-
160	7	U32	U31	√	IRDY
161	7	T30	T32	NA	-
162	7	T31	T29	NA	VREF_7
163	7	R31	R33	NA	-
164	7	R29	R30	2	-
165	7	P31	P32	√	VREF_7
166	7	P29	P30	NA	-
167	7	N31	M32	1	-
168	7	L33	N30	1	VREF_7
169	7	L32	M31	NA	-
170	7	L31	M30	2	-
171	7	J33	M29	√	-
172	7	K31	L30	√	VREF_7
173	7	H33	L29	1	-
174	7	H32	J31	NA	VREF_7
175	7	H31	K29	NA	-
176	7	G32	J30	NA	-
177	7	G31	J29	√	VREF_7
178	7	E32	E33	NA	-
179	7	F31	H29	2	-
180	7	E31	D32	1	VREF_7
181	7	C33	G29	NA	-
182	7	D31	F30	NA	-

Notes:
1. AO in the XCV812E
2. AO in the XCV405E

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
7	IO_L182P_YY	E4
2	CCLK	D24
3	DONE	AB21
NA	DXN	AB7
NA	DXP	Y8
NA	M0	AD4
NA	M1	W7
NA	M2	AB6
NA	PROGRAM	AA22
NA	TCK	E6
NA	TDI	D22
2	TDO	C23
NA	TMS	F5
0	NC	A9
0	NC	A10
0	NC	B4
0	NC	B12
0	NC	D13
1	NC	A13
1	NC	A16
1	NC	A24
1	NC	B15
1	NC	B17
2	NC	D25
2	NC	H26
2	NC	K26
2	NC	M25
2	NC	N26
3	NC	AC25
3	NC	P26
3	NC	R26
3	NC	T26
3	NC	U26

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
4	NC	AE15
4	NC	AF14
4	NC	AF16
4	NC	AF18
4	NC	AF23
5	NC	AE12
5	NC	AF3
5	NC	AF10
5	NC	AF11
5	NC	Y13
6	NC	AC1
6	NC	P1
6	NC	R2
6	NC	T1
6	NC	V1
7	NC	D1
7	NC	J1
7	NC	L1
7	NC	M1
7	NC	N1
NA	NC	T25
NA	NC	T2
NA	NC	P2
NA	NC	N25
NA	NC	L25
NA	NC	L2
NA	NC	F6
NA	NC	F25
NA	NC	F21
NA	NC	F2
NA	NC	C26
NA	NC	C25
NA	NC	C2
NA	NC	C1
NA	NC	B6

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
1	VCCO	H15
2	VCCO	N18
2	VCCO	M19
2	VCCO	M18
2	VCCO	L19
2	VCCO	K19
2	VCCO	J19
3	VCCO	V19
3	VCCO	U19
3	VCCO	T19
3	VCCO	R19
3	VCCO	R18
3	VCCO	P18
4	VCCO	W18
4	VCCO	W17
4	VCCO	W16
4	VCCO	W15
4	VCCO	V15
4	VCCO	V14
5	VCCO	W9
5	VCCO	W12
5	VCCO	W11
5	VCCO	W10
5	VCCO	V13
5	VCCO	V12
6	VCCO	V8
6	VCCO	U8
6	VCCO	T8
6	VCCO	R9
6	VCCO	R8
6	VCCO	P9
7	VCCO	N9
7	VCCO	M9
7	VCCO	M8
7	VCCO	L8

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
7	VCCO	K8
7	VCCO	J8
NA	GND	V25
NA	GND	V2
NA	GND	U17
NA	GND	U16
NA	GND	U15
NA	GND	U14
NA	GND	U13
NA	GND	U12
NA	GND	U11
NA	GND	U10
NA	GND	T17
NA	GND	T16
NA	GND	T15
NA	GND	T14
NA	GND	T13
NA	GND	T12
NA	GND	T11
NA	GND	T10
NA	GND	R17
NA	GND	R16
NA	GND	R15
NA	GND	R14
NA	GND	R13
NA	GND	R12
NA	GND	R11
NA	GND	R10
NA	GND	P25
NA	GND	P17
NA	GND	P16
NA	GND	P15
NA	GND	P14
NA	GND	P13

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
NA	GND	P12
NA	GND	P11
NA	GND	P10
NA	GND	N2
NA	GND	N17
NA	GND	N16
NA	GND	N15
NA	GND	N14
NA	GND	N13
NA	GND	N12
NA	GND	N11
NA	GND	N10
NA	GND	M17
NA	GND	M16
NA	GND	M15
NA	GND	M14
NA	GND	M13
NA	GND	M12
NA	GND	M11
NA	GND	M10
NA	GND	L17
NA	GND	L16
NA	GND	L15
NA	GND	L14
NA	GND	L13
NA	GND	L12
NA	GND	L11
NA	GND	L10
NA	GND	K17
NA	GND	K16
NA	GND	K15
NA	GND	K14
NA	GND	K13
NA	GND	K12
NA	GND	K11

Table 3: **FG676 Fine-Pitch BGA — XCV405E**

Bank	Pin Description	Pin #
NA	GND	K10
NA	GND	J25
NA	GND	J2
NA	GND	E5
NA	GND	E22
NA	GND	D4
NA	GND	D23
NA	GND	C3
NA	GND	C24
NA	GND	B9
NA	GND	B25
NA	GND	B2
NA	GND	B18
NA	GND	B14
NA	GND	AF26
NA	GND	AF1
NA	GND	AE9
NA	GND	AE25
NA	GND	AE2
NA	GND	AE18
NA	GND	AE13
NA	GND	AD3
NA	GND	AD24
NA	GND	AC4
NA	GND	AC23
NA	GND	AB5
NA	GND	AB22
NA	GND	A26
NA	GND	A1

FG676 Differential Pin Pairs

Virtex-E Extended Memory devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package.

Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair is in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 4: **FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
3	0	E13	B13	NA	IO_DLL_L21N
2	1	C13	F14	NA	IO_DLL_L21P
1	5	AB13	AF13	NA	IO_DLL_L115N
0	4	AA14	AC14	NA	IO_DLL_L115P
IOLVDS Total Pairs: 183, Asynchronous Output Pairs: 97					
0	0	F7	C4	NA	-
1	0	C5	G8	√	-
2	0	E7	D6	√	VREF
3	0	F8	A4	NA	-
4	0	D7	B5	NA	-
5	0	G9	E8	√	VREF
6	0	F9	A5	√	-
7	0	C7	D8	NA	-
8	0	E9	B7	NA	-
9	0	D9	A7	NA	-
10	0	G10	B8	NA	VREF
11	0	F10	C9	√	-
12	0	E10	A8	NA	-
13	0	D10	G11	√	-
14	0	F11	B10	√	-
15	0	E11	C10	NA	-

Table 4: **FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
16	0	D11	G12	√	-
17	0	F12	C11	√	VREF
18	0	E12	A11	√	-
19	0	C12	D12	NA	-
20	0	H13	A12	NA	VREF
21	1	F14	B13	NA	IO_LVDS_DLL
22	1	F13	E14	NA	-
23	1	A14	D14	NA	VREF
24	1	H14	C14	NA	-
25	1	C15	G14	√	-
26	1	D15	E15	√	VREF
27	1	F15	C16	√	-
28	1	D16	G15	-	-
29	1	A17	E16	√	-
30	1	E17	C17	√	-
31	1	D17	F16	NA	-
32	1	C18	F17	√	-
33	1	G16	A18	√	VREF
34	1	G17	C19	√	-
35	1	B19	D18	NA	-
36	1	E18	D19	NA	-
37	1	B20	F18	√	-
38	1	C20	G19	√	VREF
39	1	E19	G18	√	-
40	1	D20	A21	√	-
41	1	C21	F19	√	VREF
42	1	E20	B22	√	-
43	1	D21	A23	2	-
44	1	E21	C22	√	CS
45	2	E23	F22	√	DIN, D0
46	2	E24	F20	√	-
47	2	G21	G22	2	-
48	2	F24	H20	1	VREF
49	2	E25	H21	1	-

Table 4: **FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
50	2	F23	G23	√	-
51	2	H23	J20	√	VREF
52	2	G24	H22	√	-
53	2	J21	G25	2	-
54	2	G26	J22	1	-
55	2	H24	J23	√	-
56	2	J24	K20	√	VREF
57	2	K22	K21	√	D2
58	2	H25	K23	√	-
59	2	L20	J26	2	-
60	2	K25	L22	1	-
61	2	L21	L23	1	-
62	2	M20	L24	1	-
63	2	M23	M22	√	D3
64	2	L26	M21	√	-
65	2	N19	M24	2	-
66	2	M26	N20	1	VREF
67	2	N24	N21	√	-
68	2	N23	N22	√	-
69	3	P21	P23	√	-
70	3	P22	R25	1	VREF
71	3	P19	P20	2	-
72	3	R21	R22	√	-
73	3	R24	R23	√	VREF
74	3	T24	R20	1	-
75	3	T22	U24	1	-
76	3	T23	U25	1	-
77	3	T21	U20	2	-
78	3	U22	V26	√	-
79	3	T20	U23	√	D5
80	3	V24	U21	√	VREF
81	3	V23	W24	√	-
82	3	V22	W26	NA	-
83	3	Y25	V21	NA	-

Table 4: **FG676 Fine-Pitch BGA Differential Pin Pair Summary — XCV405E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
84	3	V20	AA26	√	-
85	3	Y24	W23	√	VREF
86	3	AA24	Y23	NA	-
87	3	AB26	W21	NA	-
88	3	Y22	W22	NA	VREF
89	3	AA23	AB24	NA	-
90	3	W20	AC24	√	-
91	3	AB23	Y21	√	INIT
92	4	AC22	AD26	√	-
93	4	AD23	AA20	NA1	-
94	4	Y19	AC21	√	-
95	4	AD22	AB20	√	VREF
96	4	AE22	Y18	NA	-
97	4	AF22	AA19	NA	-
98	4	AD21	AB19	√	VREF
99	4	AC20	AA18	√	-
100	4	AC19	AD20	NA	-
101	4	AF20	AB18	NA	-
102	4	AD19	Y17	NA	-
103	4	AE19	AD18	NA	VREF
104	4	AF19	AA17	√	-
105	4	AC17	AB17	NA	-
106	4	Y16	AE17	√	-
107	4	AF17	AA16	√	-
108	4	AD17	AB16	NA	-
109	4	AC16	AD16	√	-
110	4	AC15	Y15	√	VREF
111	4	AD15	AA15	√	-
112	4	W14	AB15	NA	-
113	4	AF15	Y14	NA	VREF
114	4	AD14	AB14	NA	-
115	5	AC14	AF13	NA	IO_LVDS_DLL
116	5	AA13	AF12	NA	VREF
117	5	AC13	W13	NA	-

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
5	IO_VREF_5_L198N_YY	AF9
5	IO_L199P_YY	AH9
5	IO_L199N_YY	AK9
5	IO_L200P	AF8
5	IO_L200N	AB11
5	IO_L201P	AC11
5	IO_L201N	AG8
5	IO_L202P_YY	AK8
5	IO_VREF_5_L202N_YY	AF7
5	IO_L203P_YY	AG7
5	IO_L203N_YY	AK7
5	IO_L204P	AJ7
5	IO_L204N	AD10
5	IO_L205P	AH6
5	IO_L205N	AC10
5	IO_L206P_YY	AD9
5	IO_VREF_5_L206N_YY	AG6
5	IO_L207P_YY	AB10
5	IO_L207N_YY	AJ5
5	IO_L209P_Y	AC9
5	IO_L209N_Y	AJ4
5	IO_L210P_Y	AG5
5	IO_L210N_Y	AK4
6	IO	T6
6	IO	U1
6	IO	U6
6	IO	V7
6	IO	V8
6	IO	W10
6	IO	Y10
6	IO	AA2
6	IO	AA4
6	IO	AD1

Table 5: **FG900 Fine-Pitch BGA Package — XCV812E**

Bank	Description	Pin
6	IO	AD6
6	IO	AG2
6	IO_L212N_YY	AF3
6	IO_L212P_YY	AC6
6	IO_L214N_Y	AB9
6	IO_L214P_Y	AE4
6	IO_L215N	AE3
6	IO_L215P	AH1
6	IO_L217N	AG1
6	IO_L217P	AA10
6	IO_VREF_L218N_Y	AA9
6	IO_L218P_Y	AD4
6	IO_L219N_YY	AD5
6	IO_L219P_YY	AD2
6	IO_L220N	AD3
6	IO_L220P	AF2
6	IO_L221N	AA8
6	IO_L221P	AA7
6	IO_VREF_L222N_YY	AF1
6	IO_L222P_YY	Y9
6	IO_L223N_YY	AB6
6	IO_L223P_YY	AC4
6	IO_L224N_Y	AE1
6	IO_L224P_Y	W8
6	IO_L225N	Y8
6	IO_L225P	AB4
6	IO_VREF_L226N	AB3
6	IO_L226P	W9
6	IO_L228N	AB1
6	IO_L228P	V10
6	IO_VREF	AC1
6	IO_L230N	V11
6	IO_L230P	AA3
6	IO_L232N_Y	W7